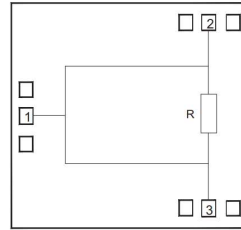


### Performance

- Frequency: 0.5~1.5GHz
- Insertion loss: 0.8dB
- Chip size: 1.70\*1.40\*0.1mm

### Function Diagram

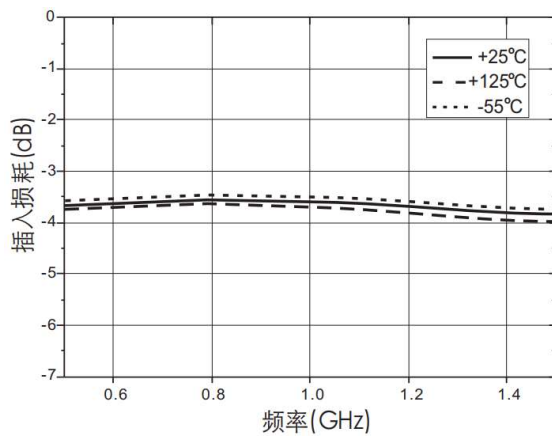


### Electrical Specifications (Ta=+25°C, 50Ω system)

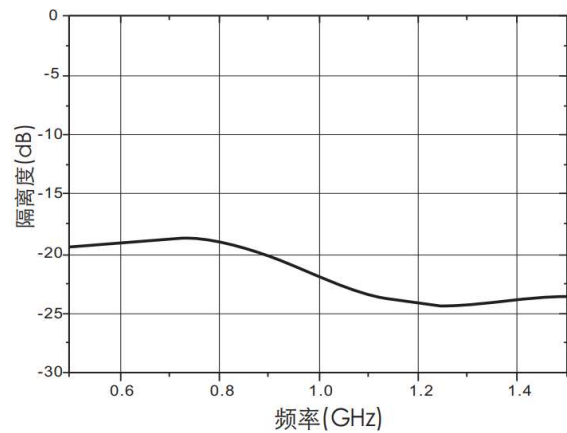
Parameter	Min	Typical	Max	Unit
Frequency Range		0.5~1.5		GHz
Insertion Loss	-	0.8	1.2	dB
Insertion Loss Ripple	-	±0.7	-	dB
Isolation	17	22	-	dB
VSWRin	15	20	-	dB
VSWRout	17	22	-	dB

### Test Curves

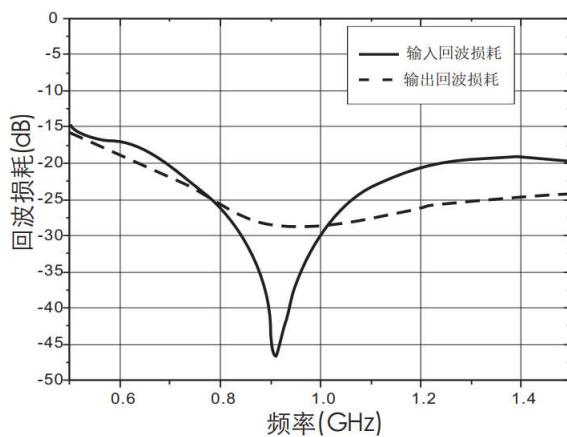
Insertion loss vs. Freq



Isolation vs. Freq



Input/Output Return Loss vs. Freq



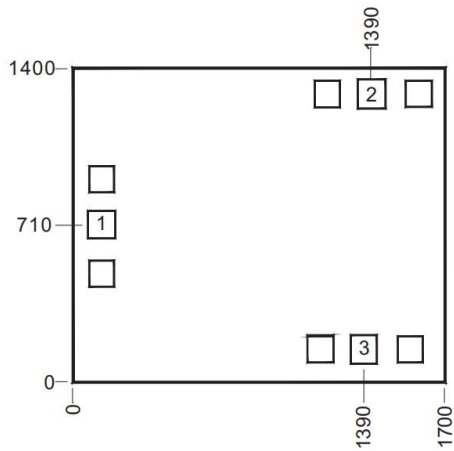
### Absolute Max Ratings

RF Input Power	+37dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C
Junction Temperature	175°C
Static Protection (HBM)	Class 1A



ELECTROSTATIC SENSITIVE DEVICE  
OBSERVE HANDLING PRECAUTIONS

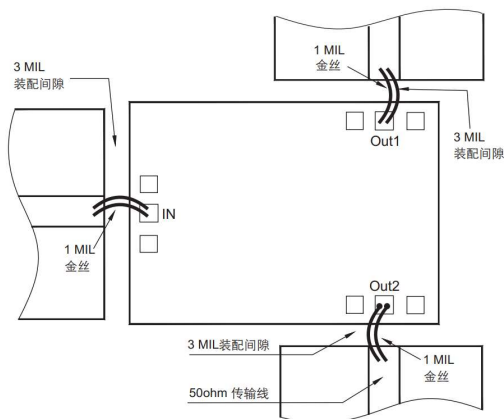
### Outline Size



### Note:

1. Unit:  $\mu\text{m}$
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads are gold plated  
Pads size:  $100 \times 100 \mu\text{m}$
5. Don't bonding on thru holes
6. Tolerance:  $\pm 50 \mu\text{m}$

### Assembly Diagram



### Bonding Definition

No.	Symbol	Description
1	In	RF Input, 50ohm
2, 3	Out1, Out2	RF Output, 50ohm
	GND	Bottom must be grounded